

ABSTRACT DEADLINE EXTENDED TO NOVEMBER 13, 2020

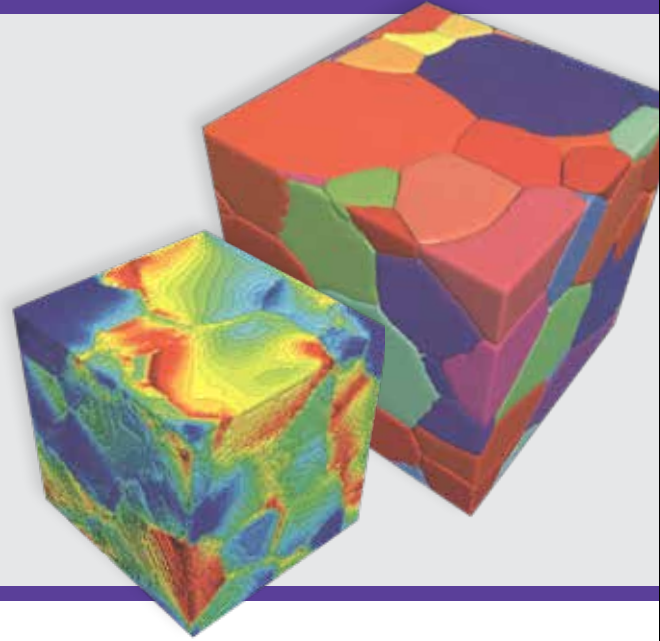
The 5th International Congress on

3DMS

3D Materials Science 2021

June 29–July 2, 2021

Hyatt Regency Washington on Capitol Hill,
Washington, D.C., USA



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- 3D data processing and reconstruction algorithms
- Process-microstructure-property relationships in 3D
- Materials dynamics in 3D
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